



Title of Change:	KAF-8300 datasheet: Update of test conditions	
Effective date:	2 February 2018	
Contact information:	Contact your local ON Semiconductor Sales Office or <John.Frenett@onsemi.com>	
Type of notification:	This Product Bulletin is for notification purposes only. ON Semiconductor will proceed with implementation of this change upon publication of this Product Bulletin.	
Change category:	<input type="checkbox"/> Wafer Fab Change <input type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input checked="" type="checkbox"/> Other <u>Documentation</u>	
Change Sub-Category(s):	<input type="checkbox"/> Manufacturing Site Change/Addition <input type="checkbox"/> Material Change <input checked="" type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Product specific change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Other: _____	
Sites Affected:	ON Semiconductor Sites: ON Rochester, New York	External Foundry/Subcon Sites: None
Description and Purpose:		
<p>In moving from one package test system to another, test conditions had to be re-specified. Changes in test temperatures and clock rate were required.</p> <p>This July 2017 change was managed from Manufacturing Test CAB T2131 which details:</p> <ol style="list-style-type: none"> 1) Table 5 (TYPICAL OPERATIONAL CONDITIONS; subtitled THE PERFORMANCE SPECIFICATIONS ARE VERIFIED USING THE FOLLOWING CONDITIONS) has been renamed; now known as Table 5 (TYPICAL OPERATING CONDITIONS; no change to subtitle). Additional updates: <ol style="list-style-type: none"> a. Readout Time was 370.36 ms; now reads 526 ms b. Horizontal Clock Frequency was 28 MHz; now reads 20 MHz c. Mode was Flush – Integrate – Readout Cycle; now reads Integrate – Readout Cycle 2) Table 6 (SPECIFICATIONS) includes the following changes: <ol style="list-style-type: none"> a. Operating Temperature was 60 deg C; now reads 30 deg C b. Engineering units for Linearity Balance had been <blank >; now reads % c. Note 6 has been deleted 3) Table 7 (OPERATIONAL CONDITIONS) has been updated: <ol style="list-style-type: none"> a. Operating Temperature was 60 deg C; now reads 30 deg C 4) Table 8 (SPECIFICATIONS) includes the following changes: <ol style="list-style-type: none"> a. Operating Temperature was 60 deg C; now reads 30 deg C b. Note 5 has been deleted 5) Table 14 (TIMING REQUIREMENTS AND CHARACTERISTICS) includes the following changes: <ol style="list-style-type: none"> a. Note 5 was augmented with the following text: <ol style="list-style-type: none"> i. Includes tv_{overclock} and th_{overclock} <p>The change will not impact form, fit, or function of KAF-8300 image sensors. Datasheet specifications are not changing. Again, changes listed above relate to test conditions used at the factory.</p>		
List of Affected Standard Parts:		
KAF-8300-AAB-CB-AA	KAF-8300-AXC-CB-AE	KAF-8300-AXC-CP-AA
KAF-8300-AAB-CB-AE	KAF-8300-AXC-CD-AA	KAF-8300-AXC-CP-AE
KAF-8300-AXC-CB-AA	KAF-8300-AXC-CD-AE	

Appendix A: Changed Products

DIKG : DIGI-KEY

Product	Customer Part Number
KAF-8300-AAB-CB-AA	
KAF-8300-AXC-CB-AA	
KAF-8300-AXC-CD-AA	
KAF-8300-AXC-CP-AA	